

RoHS

For 2Cell Solar, Synchronous Switch-Mode Charger IC

BU1840AMUV

General Description

The BU1840AMUV device provides the best system to the product charged with 1cell Li-ion battery and 3cell Nickel-metal-hydride batteries using the 2cell, 3cell, and 4cell solar panel.

It is possible to boost it according to the voltage of 2 cell solar panel with built-in the function to boost the low voltage input.

Moreover, the solar battery maximum dissipation can be drawn out with built-in the peak power track function. It is possible to select the the switching frequency according to the terminal SEL.

It is also possible to monitor the charging current by the I2C interface.

Built in heat reckless driving protection (Thermal shutdown), decrease voltage protection, and input current protection for protection function

Features

- Synchronous Switch-Mode Charger for 2Cell Solar 400mA@Battery=3.7V,VIN=1V
- MPPT control voltage range : 0.7V~1.5V
- Charging current completion voltage : 5.0V (hysteresis: 0.075V)
- Built in MPPT
- Switching frequency (160kHz,320kHz)
- Charging current monitor by I2C
- UVLO-detect Voltage:0.625V
- UVLO-release Voltage:0.700V
- Thermal Shutdown
- 24 pin VQFN024V4040 (4.1mm × 4.1mm < MAX>)

Typical Application Circuit(s)

<For 2 Cells Solar> R7 نر ژ VIN SW1,2,3 女 D1 COREVDD VINMON ,‡c₅ to batterv R1 (or Charger Control IC) OUTP1, V18 Solar Pane 声~6 ↓ C2 BU1840AMUV OUTPN AGND1,2 OUTS VIO IMON C3 SDA SCL VDD for VIO C8 ENB PGND123 OFF ON SEL PCO GND or VIN R osc -04

Applications

- Solar mobile phone
- Solar audio
- Solar portable charger
- Solar LED illumination

Package(s)

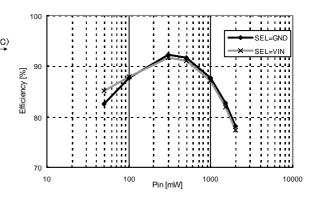
VQFN024V4040

W(Typ.) x D(Typ.) x H(Max.) 4.00mm x 4.00mm x 1.00mm



•Typical Performance characteristics

<Efficiency (for 2 cells solar)> (VINMON=1.0V, OUTS=3.7V, Pin = 50mW ~ 2W)



OProduct structure : Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays

●Absolute maximum ratings (Ta=25°C)

| Parameter | Symbol | Ratings | Unit | Conditions |
|-----------------------------|--------|----------|------|---|
| Maximum applied voltage 1 | Vmax1 | 7.0 | V | VIO,SDA,SCL,SW1,2,3, ENB COREVDD,OUTP1,2,OUTPM,OUTS |
| Maximum applied voltage 2 | Vmax2 | 2.5 | V | VIN, VINMON, V18, IMON, PCOMP, SEL, OSC |
| Power dissipation1 | Pd1 | 560 | mW | 1layer(74.2x74.2mm)boad (Surface heat radiation copper foil:6.28mm ²) |
| Power dissipation2 | Pd2 | 1766 | mW | 4layer(74.2x74.2mm)boad (1,4layer heat radiation copper foil:6.28mm ²) (2,3layer heat radiation copper foil:5500mm ²) |
| Operating temperature range | Topr | -30~+85 | °C | |
| Storage temperature range | Tstr | -55~+150 | °C | |

*1 When it is used by more than Ta=25°C, it is reduced by $5.6mW/^{\circ}C$. *1

*2 When it is used by more than Ta=25°C, it is reduced by 17.66mW/°C.

●Operating conditions (Ta=25°C)

| Parameter | Symbol | Ratings | Unit | Conditions |
|------------------------------|--------|------------|------|----------------------|
| Power supply voltage range 1 | VCC1 | 0.625~1.98 | V | VIN terminal voltage |
| Power supply voltage range 2 | VCC2 | 1.7~5.5 | V | VIO terminal |

●Electrical characteristics (Unless otherwise specified: Ta=25°C, VIN=1.0V)

| Deremeter | Currents et | | Rating | | 1.1 | Conditions |
|---|-------------|-------|--------|-------|------|---|
| Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions |
| MPPT control minimum voltage | MPPTL | - | - | 0.7 | V | VINMON-monitor |
| MPPT control maximum voltage | MPPTH | 1.5 | - | - | V | VINMON-monitor |
| MPPT-VIN control voltage resolution | PPTVT | 12.5 | 25.0 | 37.5 | mV | |
| UVLO Release Threshold | VuvloR | 0.6 | 0.7 | 0.8 | V | VIN-rising |
| UVLO Detect Threshold | VuvloD | 0.575 | 0.625 | 0.675 | V | VIN-falling |
| UVLO Hysteresis | Vuvlohys | 30 | 80 | 130 | mV | |
| MPPT start up voltage | Vst1 | 2.45 | 2.6 | 2.75 | V | COREVDD-monitor (hys=0.3V) |
| Charging current completion voltage | Vch2 | 4.93 | 5.0 | 5.07 | V | OUTS-monitor RISING. (hysteresis=0.075V) |
| Circuit current 1 (VIN-CURRENT) | ICC1 | - | - | 1.0 | mA | ENB=1V, SW=VIN |
| Circuit current 2 (OUTS-CURRENT) | ICC2 | - | - | 2 | uA | ENB=1V, OUTS,P=5.2V, COREVDD=3.7V |
| Circuit current 3 (OUTS-CURRENT) Not-Switching | ICC3 | - | - | 4 | uA | ENB=0V, OUTS,P=5.2V COREVDD=3.7V |
| Nch-SW ON registor | Rnsw | - | 60 | - | mΩ | |
| Pch-SW ON registor | Rpsw | - | 100 | - | mΩ | |
| Input over current limiter | VIIim | 3.0 | 4.0. | 5.0 | Α | |
| DCDC switching frequency 1 (SEL=VIN) | Fosc1 | 260 | 320 | 380 | kHz | OSC2OUT |
| DCDC switching frequency 2 (SEL=GND) | Fosc2 | 130 | 160 | 190 | kHz | OSC2OUT |
| Charging current voltage range | VImon | 0 | | 40 | mV | V(OUTPM)-V(OUTS) |
| Charging current monitor accuracy 1 | lmon1 | 0D | 2B | 49 | Hex | V(OUTPM)-V(OUTS)=0mV |
| Charging current monitor accuracy 2 | Imon2 | 88 | A6 | BF | Hex | V(OUTPM)-V(OUTS)=40mV |
| Logic operating clock | Logosc | - | 30 | - | kHz | C4=100pF |
| ENB "H" level voltage | Venh | 1.1 | - | - | V | POWER-OFF |
| ENB "L" level voltage | Venl | 0 | - | 0.2 | V | POWER-ON |

●Electrical characteristics (Unless otherwise specified: Ta=25°C, VIO=1.8V)

| Item | Symbol | Min. | Тур. | Max. | Unit | Conditions |
|--|--------|---------------|------|---------------|------|-------------------|
| 【I ² C input (SDA, SCL)】 | | | | | | |
| L level input voltage | VIL1 | -0.3 | - | 0.25 × VIO | V | |
| H level input voltage | VIH1 | 0.75 × VIO | - | VIO +0.3 | V | |
| Hysteresis width | Vhys1 | 0.05 × VIO | - | - | V | |
| L level output voltage (Sink current = 3mA) | VOL1 | 0 | - | 0.3 | V | SDA pin |
| Input current | lin1 | -3 | - | 3 | μA | Pin voltage=0~VIO |

●I²C BUS format

The writing/reading operation is based on the I²C slave standard.

Slave address

| I | A7 | A6 | A5 | A4 | A3 | A2 | A1 | R/W |
|---|----|----|----|----|----|----|----|-----|
| | 1 | 1 | 1 | 0 | 0 | 0 | 1 | 1/0 |

Bit Transfer

SCL transfers 1-bit data during H. SCL cannot change signal of SDA during H at the time of bit transfer. If SDA changes while SCL is H, START conditions or STOP conditions will occur and it will be interpreted as a control signal.

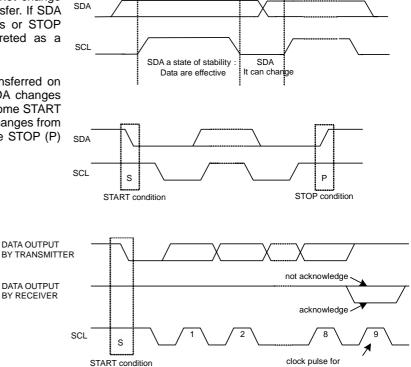
START and STOP condition

When SDA and SCL are H, data is not transferred on the I^2C - bus. This condition indicates, if SDA changes from H to L while SCL has been H, it will become START (S) conditions, and an access start, if SDA changes from L to H while SCL has been H, it will become STOP (P) conditions and an access end.

Acknowledge

Protocol

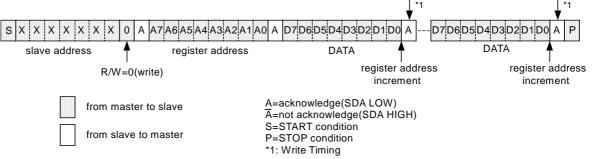
It transfers data 8 bits each after the occurrence of START condition. A transmitter opens SDA after transfer 8bits data, and a receiver returns the acknowledge signal by setting SDA to L.



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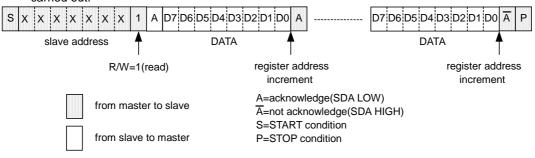
1. Writing protocol

A register address is transferred by the next 1 byte that transferred the slave address and the write-in command. The 3rd byte writes data in the internal register written in by the 2nd byte, and after 4th byte or, the increment of register address is carried out automatically. However, when a register address turns into the last address, it is set to 00h by the next transmission. After the transmission end, the increment of the address is carried out.



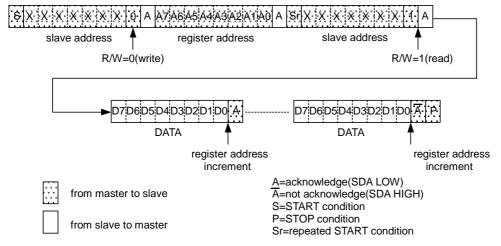
2. Reading protocol

It reads from the next byte after writing a slave address and R/W bit. The register to read considers as the following address accessed at the end, and the data of the address that carried out the increment is read after it. If an address turns into the last address, the next byte will read out 00h. After the transmission end, the increment of the address is carried out.



3. Multiple reading protocols

After specifying an internal address, it reads by repeated START condition and changing the data transfer direction. The data of the address that carried out the increment is read after it. If an address turns into the last address, the next byte will read out 00h. After the transmission end, the increment of the address is carried out.

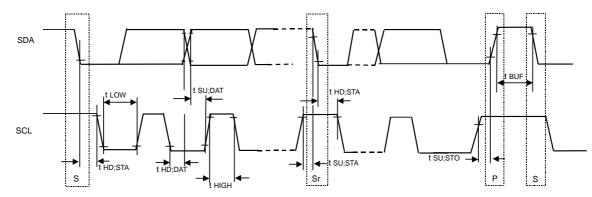


X As for reading protocol and multiple reading protocols, please do A(not acknowledge) after doing the final reading operation. It stops with read when ending by A (acknowledge), and SDA stops in the state of Low when the reading data of that time is 0. However, this state returns usually when SCL is moved, data is read, and A (not acknowledge) is done.

| ltem | Symbol | Sta | ndard-m | ode | F | ast-moc | le | Тур. |
|--|---------|------|---------|------|------|---------|------|------|
| | Symbol | Min. | Тур. | Max. | Min. | Тур. | Max. | тур. |
| [I ² C BUS format] | | | | | | | | |
| SCL clock frequency | fSCL | 0 | - | 100 | 0 | - | 400 | kHz |
| LOW period of the SCL clock | tLOW | 4.7 | - | - | 1.3 | - | - | μs |
| HIGH period of the SCL clock | tHIGH | 4.0 | - | - | 0.6 | - | - | μs |
| Hold time for a repeated START condition | tHD;STA | 4.0 | - | - | 0.6 | - | - | μs |
| Set-up time for a repeated START condition | tSU;STA | 4.7 | - | - | 0.6 | - | - | μs |
| Data hold time | tHD;DAT | 0 | - | 3.45 | 0 | - | 0.9 | μs |
| Data set-up time | tSU;DAT | 250 | - | - | 100 | - | - | ns |
| Set-up time for STOP condition | tSU;STO | 4.0 | - | - | 0.6 | - | - | μs |
| Bus free time between a STOP and START condition | tBUF | 4.7 | - | - | 1.3 | - | - | μs |

●Electrical Characteristics(Unless otherwise specified, Ta=25 °C, VIO=1.8V)

Timing diagram



Register Map

| Address | Symbol Name | R/W | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | INITIAL | Function |
|---------|----------------|-----|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|---------|----------|
| 00h | SFTRST | W | - | - | - | - | - | - | - | SFT RST | 00h | |
| 01h | ADCDATA | R | ADC DATA7 | ADC DATA6 | ADC DATA5 | ADC DATA4 | ADC DATA3 | ADC DATA2 | ADC DATA1 | ADC DATA0 | 00h | |

Please input "0" to "-".

In an empty address, there is a possibility of doing assign to the register for the test.

The access to a register for the test and an undefined register is prohibited.

The I²C control timing and the internal operation of IC timing become asynchronous relations when reading out data from the outside.

I hope measures so as not to become a problem on the application as the agreement sequence is compare three times.

•Register Explanation

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| Address | Symbol Name | R/W | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | INITIAL | データ内容 |
|---------|----------------|-----|----|----|----|----|----|----|----|------------|---------|--------------------|
| 00h | SFTRST | W | - | - | - | - | - | - | - | SFT RST | 00h | ソフトウェア リセット制御入力 |

| Bit name | Bit | Function | 0 | 1 |
|----------|-----|--------------------------------------|--------|-------|
| SFTRST | D0 | RST (All registers are initialized.) | Normal | Reset |

After initializing this all registers when SFTRST: D0=1 is done in WRITE, the value of this register returns to an initial value, too.

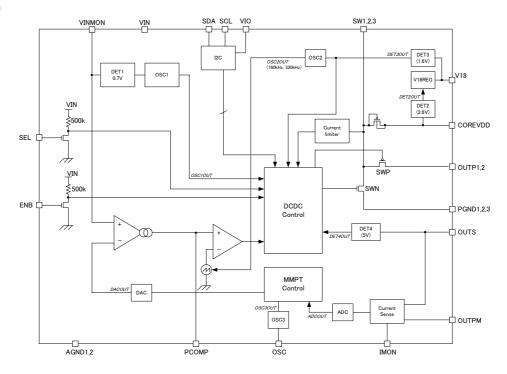
| Address | Symbol Name | R/W | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | INITIAL | データ内容 |
|---------|----------------|-----|--------------|--------------|--------------|--------------|--------------|--------------|------------------|--------------|---------|-------|
| 01h | ADCDATA | R | ADC DATA7 | ADC DATA6 | ADC DATA5 | ADC DATA4 | ADC DATA3 | ADC DATA2 | ADC DATA 1 | ADC DATA0 | 00h | |

D7-D0:

ADCDATA7-0 8bitADC data (Initial 00h)

Note) When not charging it (V18<1.6V & DET4OUT=HI <full charge>), doesn't return the acknowledge signal.

Block diagram



Block Operation Characteristics

- DET1 : The voltage of VINMON is detected. (It has hysteresis characteristics.) 0.700V-DETECT
 - 0.625V-RELEASE
- DET2 : The voltage of COREVDD (2.6V) is detected. (It has hysteresis characteristics.) 2.6V-DETECT 2.3V-RELEASE
- DET3 : The voltage of V18 is detected. (It has hysteresis characteristics.) 1.6V-DETECT
 - 1.5V-RELEASE
- DET4 : The voltage of OUTS is detected. (It has hysteresis characteristics.) 5.0V-DETECT 4.925V-RELEASE
- OSC1 : It is an oscillator. It operates at the self-excitation boost.
- OSC2 : It is an oscillator. It operates at MPPT. SEL= GND : frequency=160kHz SEL= VIN : frequency=320kHz
- OSC3 : It is an oscillator. It uses it for the clock in the MPPT-CONTROL Block and the A/D Block.
- DAC : It is D/A converter. A standard voltage of MPPT is output.
- ADC : It is A/D converter. The analogue signal amplified in the Current-Sense block is converted into the digital signal.
- Current-Sense : The OUTPM-OUTS voltage is amplified.
- V18REG : Internal power supply V18 is generated from COREVDD.
- Current-limiter : The current that flows from SW to PGND is detected.
- I2C : It is I2C interface block. VIO is made a power supply.
- MPPT-Control : To charge it by the solar battery maximum dissipation, it controls.

Charging Current Sense Register (R1)

It is necessary to decide the constant of R1 in proportion to the maximum charge current. Maximum charging current = "Maximum input power" \times "Efficiency" \div "Voltage of battery"

| Maximum charging current [mA] | R1 [mΩ] | Maximum charging current [mA] | R1 [mΩ] |
|-------------------------------------|---------|-------------------------------------|---------|
| 60 | 560 | 350 | 100 |
| 80 | 470 | 400 | 100 |
| 100 | 390 | 480 | 82 |
| 120 | 330 | 580 | 68 |
| 150 | 220 | 700 | 56 |
| 200 | 180 | 820 | 47 |
| 250 | 150 | 1000 | 39 |
| 300 | 120 | 1200 | 33 |

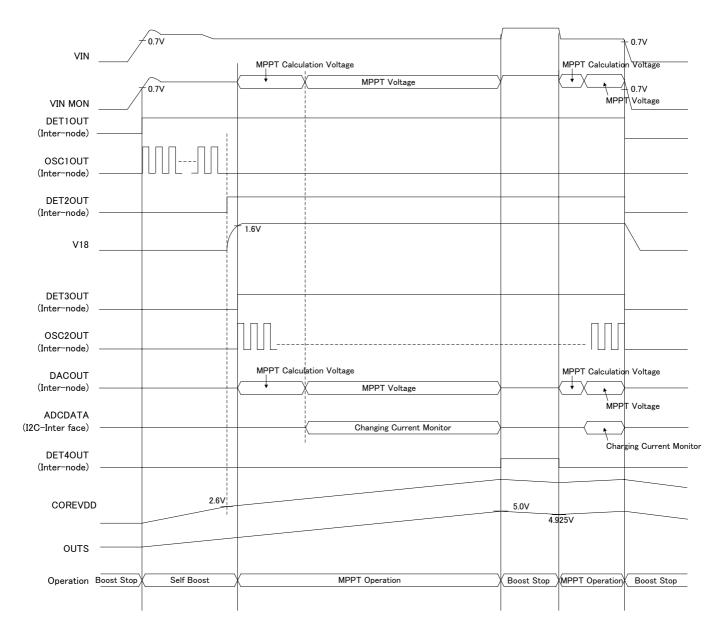
Charging Current Data

The current for each 1bit of the charge current data is decided by the following calculating formula

| R1 [mΩ] | Charging current/1bit [mA] | R1 [mΩ] | Charging current/1bit [mA] |
|---------|----------------------------------|---------|----------------------------------|
| 33 | 9.685 | 150 | 2.131 |
| 39 | 8.195 | 180 | 1.776 |
| 47 | 6.800 | 220 | 1.453 |
| 56 | 5.707 | 270 | 1.184 |
| 68 | 4.700 | 330 | 0.9685 |
| 82 | 3.898 | 390 | 0.8195 |
| 100 | 3.196 | 470 | 0.6800 |
| 120 | 2.663 | 560 | 0.5707 |

Charging current =(Charging current data[Hex] - 2B[Hex]) × "Charging current / 1bit"

Operating Sequence



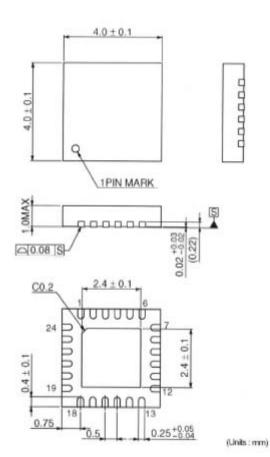
Note) When MPPT operating, it is calculated of MPP each 158mS. (Logosc=30kHz) The amount of the MPP voltage change is 25mV step.

Pin Layout

| No. | PIN Name | F unction | ESD Diode | |
|-----|----------|---|-----------|----------|
| | | Function | High side | GND side |
| 1 | SCL | I2C Interface clock input pin | VIO | AGND |
| 2 | SDA | I2C Interface data input and output pin | VIO | AGND |
| 3 | VINMON | VIN monitor pin | - | AGND |
| 4 | IMON | - | COREVDD | AGND |
| 5 | OUTS | Charging current sense pin 1 | - | AGND |
| 6 | AGND1 | GND pin | COREVDD | AGND |
| 7 | OUTP1 | Output voltage pin | - | AGND |
| 8 | OUTP2 | Output voltage pin | - | AGND |
| 9 | SW1 | Inductor connect pin | - | - |
| 10 | SW2 | Inductor connect pin | - | - |
| 11 | SW3 | Inductor connect pin | - | - |
| 12 | OUTPM | Charging current sense pin 2 | - | AGND |
| 13 | PGND1 | GND pin | COREVDD | AGND |
| 14 | PGND2 | GND pin | COREVDD | AGND |
| 15 | PGND3 | GND pin | COREVDD | AGND |
| 16 | COREVDD | Internal power supply 1 | COREVDD | AGND |
| 17 | V18 | Internal power supply 2 | V18 | AGND |
| 18 | SEL | DCDC switching frequency changing pin SEL = GND : 160kHz SEL = VIN : 320kHz | VIN | AGND |
| 19 | VIN | Solar battery input pin | VIN | AGND |
| 20 | OSC | Logic frequency adjustment pin | V18 | AGND |
| 21 | PCOMP | Phase compensation pin | V18 | AGND |
| 22 | AGND2 | GND pin | V18 | AGND |
| 23 | ENB | Chip enable pin (ON:L、OFF:H) | - | AGND |
| 24 | VIO | Power supply pin for interface When I2C Interface is not used, please connect VIO pin to COREVDD pin. | VIO | AGND |

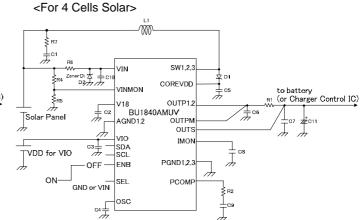
Package Diagram

VQFN024V4040VQ



How to select parts of application

<For 2 Cells Solar> -000 ₹ R7 ⊭⊶ SW1.2. VIN <u>∔</u>°'0 DI COREVED VINMON åcs to battery (or Charger Control IC) V18 00 BU1840AMUV OUTP1. Solar Pane 02 7 OUTPM # cu OUTS vio IMON SDA SCL _ VDD for VIC CE PGND1.2. OFF ENB ON SEL PCOM GND or VIN ารด 04 ₩



| | Value | Maker | Parts |
|-----|----------------------|-------|-------|
| R1 | ※ 1 | - | - |
| R2 | 24kΩ | - | - |
| R3 | 10Ω | - | - |
| R7 | 100mΩ | - | - |
| C1 | 200uF | - | - |
| C2 | 0.47uF | - | - |
| C3 | 0.1uF | - | - |
| C4 | 100pF | - | - |
| C5 | 22uF | - | - |
| C6 | 2.2uF | - | - |
| C7 | 100uF ^{**2} | - | - |
| C8 | 22nF | - | - |
| C9 | 47nF | - | - |
| C10 | 10uF | - | - |
| C11 | 470uF ^{**2} | - | - |
| L1 | 4.7uH∼10uH | TOKO | D128C |
| D1* | SBD | - | - |

| | Value | Maker | Parts |
|-----|----------------------|---------|-------|
| R1 | ※ 1 | - | - |
| R2 | 24kΩ | - | - |
| R3 | 10Ω | - | - |
| R4 | 100kΩ | - | - |
| R5 | 100kΩ | - | - |
| R6 | 1kΩ | - | - |
| R7 | 100mΩ | - | - |
| C1 | 200uF | - | - |
| C2 | 0.47uF | - | - |
| C3 | 0.1uF | - | - |
| C4 | 100pF | - | - |
| C5 | 22uF | - | - |
| C6 | 2.2uF | - | - |
| C7 | 100uF ^{**2} | - | - |
| C8 | 22nF | - | - |
| C9 | 47nF | - | - |
| C10 | 10uF | - | - |
| C11 | 470uF ^{**2} | - | - |
| L1 | 4.7uH∼10uH | токо | D128C |
| D1* | SBD | - | - |
| D2 | Zener Di | RENESAS | HZ2A1 |

X1 Please set a optimal value for R1 depending on maximum charging current. For details, please see p.8 "Charge Current Sense Register (R1)".

%2 Recommended capacitance value of output (OUTS pin) is equivalent to at least 570uF, it is the total of C7(ceramic capacitors) and C11(aluminum electrolytic capacitors) or C7(ceramic capacitors) and C11(tantalum capacitors). When select the ceramic capacitor, it takes some consideration of DC bias effect(s). (Recommended pressure capacity:over 10V) With sensitive application to output ripple voltage, taking measures to reduce ESR(Equivalent Series Resistance) such as increasing of ceramic capacitor or parallel capacitor.

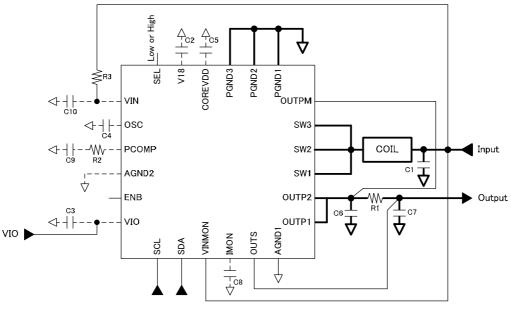
* On BU1840AMUV, output voltage (OUTS pin voltage) rise up to 5.07V; it is the highest value of the charge current completion voltage. Please insert the charging control IC between BU1840AMUV output and secondary battery as necessary.

* When I2C interface is not in use, please connect VIO pin with COREVDD pin directly.

* In case of charging of the battery with low voltage (less than 3.0V), There is a probability of the emergence of the pattern periodically repeating MPPT active/non-active mode and it will cause noise. Please insert SBD between SW pin and COREVDD pin to reduce such noise as necessary.

Notes of board layout

BU1840AMUV is switching DCDC converter, so characteristics of noise and etc changing by board layout. Please note the following respect besides a general board layout matter when you make PCB.



----- Line Please shorten.

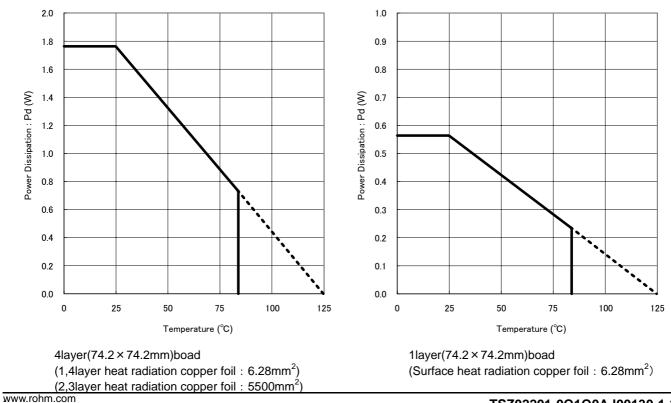
About heat loss

In the heat design, please operate it in the following condition.

(Please consider the margin etc. because the following temperature is a guarantee temperature.)

- 1. Surrounding temperature Ta must be 85°C or less.
- 2. Loss of IC must be permissible loss Pd or less.

The allowable dissipation (Pd) characteristics are described below.



Caution on use

(1) Absolute Maximum Ratings

An excess in the absolute maximum rating, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) The power supply and the GND lines

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. Please take care about interference by common impedance of the wiring pattern when there are two or more power supply and GND line. For the GND line, please note the separation of the large current route and the small signal route including the external circuit.Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(3) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state.

(4) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.

(5) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.

(6) Input terminals

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage or within the guaranteed value of electrical characteristics.

(7) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

(8) Thermal design

Perform thermal design in which there are adequate margins by taking into account the permissible dissipation (Pd) in actual states of use. Moreover, please use it within the range where output Tr doesn't exceed the rated voltage and ASO.

(9) Rush current

In CMOS IC, when the power supply is turned on rush current might flow momentarily in logical internal irregular state. Therefore, note drawing the capacity of the power supply coupling, the power supply, and width and drawing the GND pattern wiring, please.

(10) Test terminal and unused terminal processing

Please process a test terminal and unused terminal according to explanations of the function manual and the application note, etc. to be unquestionable while real used. Moreover, please inquire of the person in charge of our company about the terminal without the explanation especially.

(11)Content of material

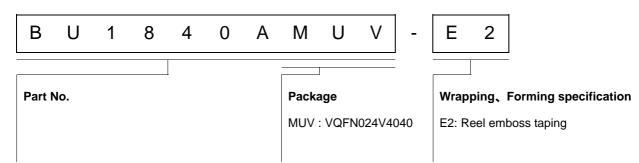
The application notes etc. are the design material to design the application, and no one of the content securing it. Please decide the application after it examines enough and it evaluates it including external parts.

Status of this document

The Japanese version of this document is formal specification. A customer may use this translation version only for a reference to help reading the formal version.

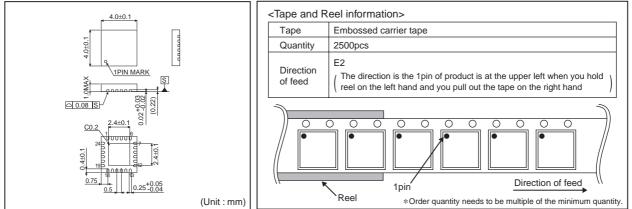
If there are any differences in translation version of this document formal version takes priority

Ordering part number



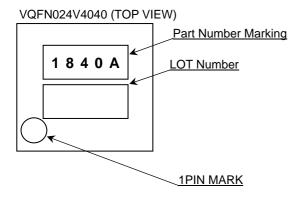
Physical Dimension Tape and Reel Information

VQFN024V4040



Marking Diagram(s)

www.rohm.com



Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

| JAPAN | USA | EU | CHINA |
|--------|--------|------------|---------|
| CLASSⅢ | CLASSⅢ | CLASS II b | |
| CLASSⅣ | | | CLASSII |

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [C] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

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- 1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data. ROHM shall not be in any way responsible or liable for infringement of any intellectual property rights or other damages arising from use of such information or data.:
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Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;

- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);

- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;

- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком):

- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

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ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



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